

4. A sealing structure for multi-chip modules as in claim 2 wherein the intervening member comprises packing.

5. (Amended) A sealing structure for multi-chip modules as in claim 1 wherein the intervening member is slidably disposed between the frame and the cap.

6. (Amended) A sealing structure for multi-chip modules as in claim 5 wherein the intervening member comprises plastic material.

7. A sealing structure for multi-chip modules as in claim 1 wherein the cap comprises an air-cooled heat sink.

8. A sealing structure for multi-chip modules as in claim 1 wherein the wiring board comprises a ceramic material, the cap comprises at least one of aluminum and copper, and the frame comprises a ferronickel alloy.

9. (Amended) A sealing structure for multi-chip modules comprising:
a wiring board having one face mounted with a plurality of semiconductor devices and another face having connecting pins arranged thereover;

a first frame having a thermal expansion coefficient compatible with that of the wiring board, the first frame provided on a periphery of the face of the wiring board mounted with the semiconductor devices;

a second frame disposed over the first frame;

a cap having a circumference and having a thermal expansion coefficient different from that of the first and second frames and covering the plurality of semiconductor devices;

a heat conducting material disposed between the cap and the plurality of semiconductor devices for transmitting heat from the semiconductor devices to the cap;

an attachment to fix the first frame and the wiring board to each other;

a fastener for fastening the first and second frames and the cap together via an intervening member,

the cap being spaced apart from the first and second frames by the intervening member.

10. A sealing structure for multi-chip modules as in claim 9 wherein O ring grooves are provided in one face of the first frame and one face of the second frame, and the cap is fastened between the first frame and the second frame using at least one O ring.

11. A sealing structure for multi-chip modules as in claim 10 wherein an elastic member is provided between a side face of the cap and a face of the first frame.

12. A sealing structure for multi-chip modules as in claim 9 wherein elastic packing is provided between the first frame and the second frame so as to cover the circumference of the cap.

13. - 15. These claims have been canceled by this amendment.

IN THE DRAWINGS:

Please amend Fig. 5 to include the legend "PRIOR ART." Enclosed herewith is a marked up sheet of Fig. 5, showing in red ink the proposed drawing amendment.